2SA1501

Silicon PNP epitaxial planar type

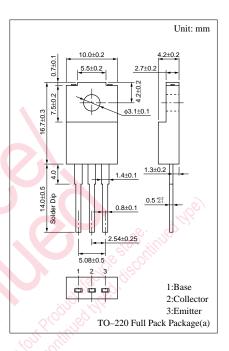
For power switching

Features

- High-speed switching
- High collector to base voltage V_{CBO}
- Wide area of safe operation (ASO)
- Satisfactory linearity of foward current transfer ratio h_{FE}
- Full-pack package which can be installed to the heat sink with one screw

Parameter		Symbol	Ratings	Unit		
Collector to base voltage		V _{CBO}	-400	V		
Collector to emitter voltage		V _{CEO}	-400	V		
Emitter to base voltage		V _{EBO}	-7	V		
Peak collector current		I _{CP}	-8	Α		
Collector current		I _C	-5	А		
Collector power	$T_C=25^{\circ}C$	D	40	W		
dissipation	Ta=25°C	P _C	2.0	W		
Junction temperature		Tj	150	°C		
Storage temperature		T _{stg}	-55 to +150	°C		

Absolute Maximum Ratings $(T_c=25^{\circ}C)$

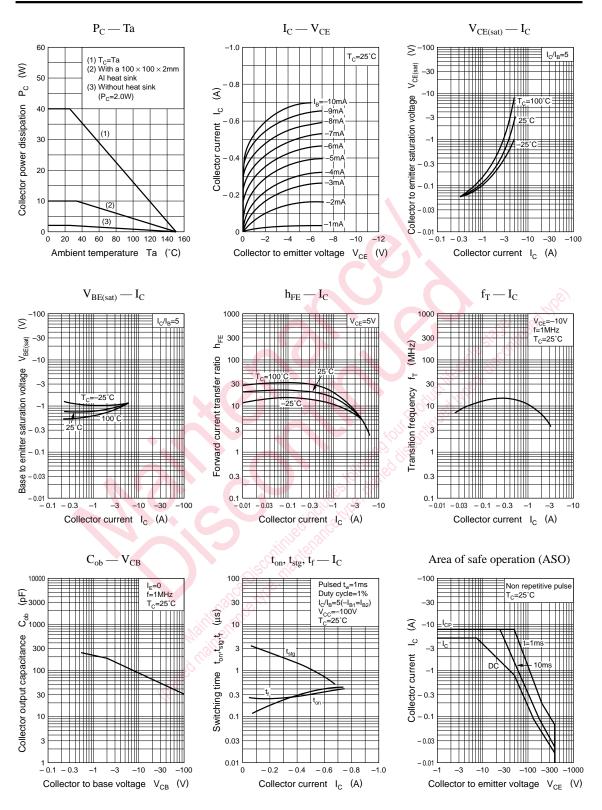


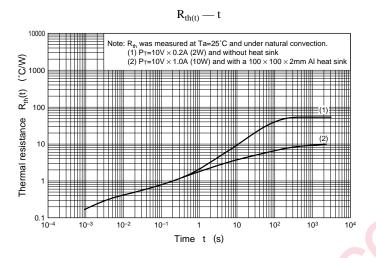
Electrical Characteristics $(T_c=25^{\circ}C)$

Parameter	Symbol	Conditions	min	typ	max	Unit
Collector cutoff current	I _{CBO}	$V_{CB} = -400V, I_E = 0$			-100	μΑ
Emitter cutoff current	I _{EBO}	$V_{\rm EB} = -7V, I_{\rm C} = 0$			-100	μΑ
Collector to emitter voltage	V _{CEO}	$I_{\rm C} = -10 {\rm mA}, I_{\rm B} = 0$	-400			V
Forward current transfer ratio	h _{FE1} *	$V_{CE} = -5V, I_C = -0.5A$	20		100	
	h _{FE2}	$V_{CE} = -5V, I_C = -2A$	8			
Collector to emitter saturation voltage	V _{CE(sat)}	$I_{\rm C} = -2A, I_{\rm B} = -0.4A$			-1.0	V
Base to emitter saturation voltage	V _{BE(sat)}	$I_C = -2A, I_B = -0.4A$			-1.5	v
Transition frequency	f _T	$V_{CE} = -10V, I_{C} = -0.5A, f = 1MHz$		15		MHz
Turn-on time	t _{on}	$I_{\rm C} = -2A$,			1.0	μs
Storage time	t _{stg}	$I_{B1} = - \ 0.4 A, \ I_{B2} = 0.4 A,$			2.5	μs
Fall time	t _f	$V_{CC} = -100V$			1.0	μs

*hFE1 Rank classification

Rank	Q	Р		
h _{FE1}	20 to 60	50 to 100		





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